



ADVANCED PROGRAMME AND REGISTRATION FORM



7th European Advanced Technology Workshop on Micropackaging and Thermal management

February 1 & 2, 2012

MERCURE OCEANIDE VIEUX PORT SUD Hotel

Quai Louis Prunier 17000 La Rochelle France
Tel : 33 (0) 5 46 50 61 50/Fax : 33 (0) 5 46 41 24 31
Email : H0569@accor.com.

**Hotel reservations will be made by the
organizing committee
Reduced fare train tickets**

**Workshop arrival day:
Tuesday January 31, evening**



WORKSHOP COMMITTEE:

Conference chairman:

France: Sandrine LELONG- FENEYROU (ZODIAC AEROSPACE)

Technical Program Committee:

France: Pierre LEWANDOWSKI (CONTINENTAL AUTOMOTIVE),
Michel MASSIOT (EGIDE),
Michel MERMET-GUYENNET (ALSTOM TRANSPORTS),
Gilles POUPON (CEA - LETI),
Claude SARNO (THALES AVIONICS),
Richard SEDDON (TECNALIA AEROSPACE),
Spain : Nick CHANDLER (BAE SYSTEMS),
United Kingdom: Dave SAUMS (DS&A LLC),
USA:

The Workshop will present improvements in thermal management materials, components and systems, to provide innovative packaging and cooling solutions for highly integrated power, RF, microwave and other devices and sub-systems.

Increases in functionality, complexity, miniaturisation, operating temperature and power output will require advances in thermal solutions at many levels, for military, aerospace, consumer and industrial systems.

Industry transition to SiC and GaN devices allows higher operating temperatures with higher heat flux but also greater reliability; these trends also require improvements and changes in packaging and thermal materials.

Thermal management has been clearly identified, in industry technology roadmaps worldwide, as a crucial constraint in packaging at all levels.

A CD ROM including the presentations will be distributed to the attendees.

- ☛ Early Registration ends January 13, 2012
- ☛ Final Registration ends on January 24, 2012
- ☛ « Formulaire de Convention de formation sur demande »

Organized by:

International Microelectronics And Packaging Society France
49 rue Lamartine 78035 Versailles

Tel : + 33 (0) 1 39 67 17 73/ Fax : + 33 (0) 1 39 02 71 93 E-mail : imaps.france@imapsfrance.org

CONFERENCES SCHEDULE (Provisional as of November 25, 2011)

FEBRUARY 1st, 2012 (Wednesday)

- 09:00 am** *Opening address: J.M. Yannou, President of IMAPS-France*
- 09:15 am** **Keynote**
Universal Test System for the Characterization of the Most Common Thermal Interface Materials
M. AboRas, Berliner Nanotest and Design Gmbh (Germany)
- 10:00 am – 10:30 am** **Coffee break/ Table Top Exhibition**
- SESSION 1 THERMAL INTERFACE MATERIALS**
Chairs : B. Braux, Astrium / M.Massiot, Egide
- 10:30 am** **Thermal Interface Material Performance Comparison**
A. de Bibikoff, **S. Lelong-Feneyrou**, Zodiac Data Systems (France)
- 11:00 am** **Cooling from Down Under –Thermally Conductive Underfill**
P. Hough, Lord Corporation (Germany)
- 11:30 am** **Classifying and Understanding Thermal Interface Materials for Power LED Applications**
D.L. Saums, DS&A LLC (United States)
- 12:00 am – 1:30 pm** **Lunch**
- SESSION 2 MEASUREMENT, MODELING & TESTS**
Chairs : C. Sarno, Thales Avionics / N. Chandler, BAE Systems
- 01:30 pm** **Transient Two-Physics Simulation of an Electronic Module**
J-L Blanchard, Valeo Geeds (France),
- 02:00 pm** **Thermal Characterization and Reliability Testing of High Power Electronics**
A. Vaas-Varnai, Mentor Graphics (Hungary)
- 02:30 pm** **Thermal Experimental & Simulation Investigations on New Lead Frame Based LED Packages**
B. Pardo, Cea-Leti (France)
- 03:00 pm** **New approach to thermal drift and gain non-uniformity correction in Microbolometer Detectors**
B. Wiecek, Technical University of Lodz (Poland)
- 03:30 – 04:15 pm** **Coffee Break/Table Top Exhibition**
- SESSION 3 MATERIALS**
Chairs: R. Seddon, Tecnalina / S Lelong-Feneyrou, Zodiac Aerospace
- 04:15 pm** **Long Term Stability of Various Aluminium Graphite Composites**
K. Höll, Hoffmann & Co Elektrokohle (Austria)
- 04:45 pm** **An Innovative Process to Fabricate Interphase-free Copper Diamond Composite Films**
T. Guillemet, ICMCB-CNRS Université de Bordeaux 1 (France)
- 05:15 pm** **End of session**
- 08:00 pm** **Dinner « CASINO BARRIERE Esplanade du Mail La Rochelle »**

FEBRUARY 2, 2012 (Thursday)

SESSION 4 METAL INTERFACE MATERIALS

Chairs : M. AboRas, Berliner Nanotest and Design GmbH / D Saums, DS & A LLC

- 09:00 am Optimization of a Flux-less Metal Interface Material by Reflow in a Vacuum Furnace
B. Wilson, SST International (United States)
- 09:30 am SLID Bonding for Thermal Interfaces – Thermal Performance
A. Larsson, Sintef (Norway)
- 10:00 am Solder-TIMs (Thermal Interface materials) – An Advanced Thermal Management Solution
K. Vijay, Indium Corporation of Europe (United Kingdom)

10:30 am – 11:00 am

POSTER SESSION

Coffee break/ Table top Exhibition

SESSION 5 APPLICATIONS

Chairs: P. Lewandowski, Continental Automotive / M. Mermet-Guyennet, Alstom Transport

- 11:00 am Analysis of Innovation Trends in packaging for Power Modules
A. Avron, Yole Développement (France)
- 11:30 am FP7 advanced GaN packaging “AGAPAC” 3rd year Progress.
O. Vendier, (hales Alenia Space (France)
- 12:00 am Cooling of a 12 kW DC/DC Converter Demonstrator
V. Rebeyrotte, Airbus (France)

12:30 am – 2:00 pm

Lunch

SESSION 6 COOLING SOLUTIONS

Chairs: G.de MEY, University of Ghent / A. Val, 3 D Plus

- 02:00 pm Unsteady Heat Transfer in Heated Conduits using Small-Scale Vorticity Concentrations effected by Vibrating Reeds
A. Glezer, Georgia Institute of Technology (United States)
- 02:30 pm CISSOID HADES®: Enabling High Power Density through Higher Temperature Gate-Drivers in New Generation of SiC/ GaN Power Modules
J.C. Doucet, CISSOID (Belgium)
- 03:00 pm Phase Change Materials for Missiles Electronics
F. Conseil, MBDA Missile Systems (France)
- 03:30 pm Development of Copper-Graphite Thermal Core Printed Circuit Boards
D. L Saums, (DS & A LLC), R. A Hay, (Metal Matrix Cast Composites), United States
- 04:00 pm End of session / Final Coffee / Departure

NEXT 2012 EVENT :

MINAPAD 2012, April 25 & 26 - Grenoble, France

REGISTRATION FORM

Early Registration ends January 13, 2012
Final Registration ends on January 24, 2012

RETURN REGISTRATION FORM ADDRESS :

INTERCONEX Florence Vireton 49 rue Lamartine 78035 Versailles France tel. : +33 (0) 1 39 67 17 73
fax : +33 (0) 1 39 02 71 93 e-mail : imaps.france@imapsfrance.org Web site : www.imapsfrance.org

WORKSHOP FEES: These fees include: Hotel for 2 nights (arrival on Tuesday), lunches and dinners for 2 days.

SPEAKERS/CHAIRS/TECHNICAL COMMITTEE 441.47 VAT excluded 528 € VAT

Please confirm your participation for first day dinner (January 31, 2012) at 8 pm

CONFERENCE ATTENDEES 2 DAYS

Before January 16, 2012

IMAPS MEMBER 557, 69 VAT €* excluded 667 €VAT included

IMAPS NON MEMBER 652, 17 VAT €* excluded 780 €VAT included

After January 13, 2012

IMAPS MEMBER 652, 17 €VAT* excluded 780 €VAT included

IMAPS NON MEMBER 744, 15 €VAT* excluded 890 €VAT included

Please confirm your participation for first day dinner (January 31, 2012)-dinner at 8 pm

Vegetarian Food

ATTENDEES ONE DAY

225.75 €VAT excluded 270 €VAT* (lunch included, no hotel).

February 1

February 2

STUDENTS

87.79 €VAT Excluded 105 € VAT (lunch excluded, no hotel)

TOTAL FEES

VAT included :€ *No refund in case of cancellation.

***For foreign companies, VAT will not be charged. VAT excluded€**

PAYMENT MEANS: By bank transfer or by cheque to the order of INTERCONEX, cash. No credit card accepted.

INTERCONEX BANK REFERENCES

BANK CODE 30004 AGENCY CODE 00859 ACCOUNT NUMBER 00010022786 RIB KEY 63 BANK ADDRESS : BNP PARIBAS VERSAILLES ET GX (00859) BIC BNPAFRPPVRS
IBAN FR 76 3000 4008 5900 0100 22 78 663
BNP PARIBAS Agency Versailles ETATS GENERAUX 36 rue des Etats Généraux 78002 Versailles France

ATTENDEE ADDRESS

NAME.....FIRST NAME.....
COMPANY/ORGANIZATION
YOUR VAT NUMBER.....
FUNCTION.....
ADDRESS.....
.....
Zip.....City.....Country.....
Phone.....Fax.....
E-mail.....
INVOICE ADDRESS (if different of above).....
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IMAPS MEMBERSHIP NUMBER.....